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#### Details

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Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I <sup>2</sup> C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	8KB (4K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf4321t-i-ml

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## 2.6.5.1 Compensating with the EUSART

An adjustment may be required when the EUSART begins to generate framing errors or receives data with errors while in Asynchronous mode. Framing errors indicate that the device clock frequency is too high. To adjust for this, decrement the value in OSCTUNE to reduce the clock frequency. On the other hand, errors in data may suggest that the clock speed is too low. To compensate, increment OSCTUNE to increase the clock frequency.

### 2.6.5.2 Compensating with the Timers

This technique compares device clock speed to some reference clock. Two timers may be used; one timer is clocked by the peripheral clock, while the other is clocked by a fixed reference source, such as the Timer1 oscillator.

Both timers are cleared, but the timer clocked by the reference generates interrupts. When an interrupt occurs, the internally clocked timer is read and both timers are cleared. If the internally clocked timer value is much greater than expected, then the internal oscillator block is running too fast. To adjust for this, decrement the OSCTUNE register.

# 2.6.5.3 Compensating with the CCP Module in Capture Mode

A CCP module can use free running Timer1 (or Timer3), clocked by the internal oscillator block and an external event with a known period (i.e., AC power frequency). The time of the first event is captured in the CCPRxH:CCPRxL registers and is recorded for use later. When the second event causes a capture, the time of the first event is subtracted from the time of the second event. Since the period of the external event is known, the time difference between events can be calculated.

If the measured time is much greater than the calculated time, the internal oscillator block is running too fast. To compensate, decrement the OSCTUNE register. If the measured time is much less than the calculated time, the internal oscillator block is running too slow. To compensate, increment the OSCTUNE register.

### 5.1.2.2 Return Stack Pointer (STKPTR)

The STKPTR register (Register 5-1) contains the Stack Pointer value, the STKFUL (Stack Full) status bit and the STKUNF (Stack Underflow) status bits. The value of the Stack Pointer can be 0 through 31. The Stack Pointer increments before values are pushed onto the stack and decrements after values are popped off the stack. On Reset, the Stack Pointer value will be zero. The user may read and write the Stack Pointer value. This feature can be used by a Real-Time Operating System (RTOS) for return stack maintenance.

After the PC is pushed onto the stack 31 times (without popping any values off the stack), the STKFUL bit is set. The STKFUL bit is cleared by software or by a POR.

The action that takes place when the stack becomes full depends on the state of the STVREN (Stack Overflow Reset Enable) configuration bit. (Refer to **Section 23.1 "Configuration Bits**" for a description of the device configuration bits.) If STVREN is set (default), the 31st push will push the (PC + 2) value onto the stack, set the STKFUL bit and reset the device. The STKFUL bit will remain set and the Stack Pointer will be set to zero.

If STVREN is cleared, the STKFUL bit will be set on the 31st push and the Stack Pointer will increment to 31. Any additional pushes will not overwrite the 31st push and STKPTR will remain at 31.

When the stack has been popped enough times to unload the stack, the next pop will return a value of zero to the PC and sets the STKUNF bit, while the Stack Pointer remains at zero. The STKUNF bit will remain set until cleared by software or until a POR occurs.

Note:	Returning a value of zero to the PC on an						
	underflow has the effect of vectoring the						
	program to the Reset vector, where the						
	stack conditions can be verified and						
	appropriate actions can be taken. This is						
	not the same as a Reset, as the contents						
	of the SFRs are not affected.						

### 5.1.2.3 PUSH and POP Instructions

Since the Top-of-Stack is readable and writable, the ability to push values onto the stack and pull values off the stack without disturbing normal program execution is a desirable feature. The PIC18 instruction set includes two instructions, PUSH and POP, that permit the TOS to be manipulated under software control. TOSU, TOSH and TOSL can be modified to place data or a return address on the stack.

The PUSH instruction places the current PC value onto the stack. This increments the Stack Pointer and loads the current PC value onto the stack.

The POP instruction discards the current TOS by decrementing the Stack Pointer. The previous value pushed onto the stack then becomes the TOS value.

# REGISTER 5-1: STKPTR: STACK POINTER REGISTER

	R/C-0	R/C-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0				
	STKFUL <sup>(1)</sup>	STKUNF <sup>(1)</sup>	—	SP4	SP3	SP2	SP1	SP0				
	bit 7							bit 0				
bit 7	STKFUL: St	tack Full Flag	bit <sup>(1)</sup>									
	1 = Stack be 0 = Stack ha	ecame full or o as not become	overflowed e full or over	rflowed								
bit 6	STKUNF: Stack Underflow Flag bit <sup>(1)</sup>											
	1 = Stack underflow occurred											
	0 = Stack underflow did not occur											
bit 5	Unimpleme	nted: Read a	<b>s</b> '0'									
bit 4-0	<b>SP4:SP0:</b> S	tack Pointer L	ocation bits	6								
	Note 1:	Bit 7 and bit 6	are cleared	d by user so	ftware or by	/ a POR.						

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented	C = Clearable only bit
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

# 6.5 Writing to Flash Program Memory

The minimum programming block is 4 words or 8 bytes. Word or byte programming is not supported.

Table writes are used internally to load the holding registers needed to program the Flash memory. There are 8 holding registers used by the table writes for programming.

Since the Table Latch (TABLAT) is only a single byte, the TBLWT instruction may need to be executed 8 times for each programming operation. All of the table write operations will essentially be short writes because only the holding registers are written. At the end of updating the 8 holding registers, the EECON1 register must be written to in order to start the programming operation with a long write. The long write is necessary for programming the internal Flash. Instruction execution is halted while in a long write cycle. The long write will be terminated by the internal programming timer.

The EEPROM on-chip timer controls the write time. The write/erase voltages are generated by an on-chip charge pump, rated to operate over the voltage range of the device.

Note: The default value of the holding registers on device Resets and after write operations is FFh. A write of FFh to a holding register does not modify that byte. This means that individual bytes of program memory may be modified, provided that the modification does not attempt to change any bit from a '0' to a '1'. When modifying individual bytes, it is not necessary to load all 8 holding registers before executing a write operation.

# FIGURE 6-5: TABLE WRITES TO FLASH PROGRAM MEMORY



#### 6.5.1 FLASH PROGRAM MEMORY WRITE SEQUENCE

The sequence of events for programming an internal program memory location should be:

- 1. Read 64 bytes into RAM.
- 2. Update data values in RAM as necessary.
- 3. Load Table Pointer register with address being erased.
- 4. Execute the row erase procedure.
- 5. Load Table Pointer register with address of first byte being written.
- 6. Write the 8 bytes into the holding registers.
- 7. Set the EECON1 register for the write operation:
  - set EEPGD bit to point to program memory;
  - clear the CFGS bit to access program memory;
  - set WREN to enable byte writes.
- 8. Disable interrupts.

- 9. Write 55h to EECON2.
- 10. Write 0AAh to EECON2.
- 11. Set the WR bit. This will begin the write cycle.
- 12. The CPU will stall for duration of the write (about 2 ms using internal timer).
- 13. Repeat from step 5 seven more times.
- 14. Re-enable interrupts.
- 15. Verify the memory (table read).

This procedure will require about 18 ms to update one row of 64 bytes of memory. An example of the required code is given in Example 6-3.

Note: Before setting the WR bit, the Table Pointer address needs to be within the intended address range of the 8 bytes in the holding register.

### 9.1 INTCON Registers

The INTCON registers are readable and writable registers, which contain various enable, priority and flag bits.

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global interrupt enable bit. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt. This feature allows for software polling.

# REGISTER 9-1: INTCON: INTERRUPT CONTROL REGISTER

	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x						
	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF						
	bit 7							bit 0						
		<b>.</b>												
bit 7	GIE/GIEH: (	Jobal Interrup	t Enable bi	I										
	<u>When IPEN = 0:</u> 1 – Enables all unmasked interrupts													
	0 = Disables	$\mu = \Box \text{ nables all unmasked interrupts}$ $0 = \text{Disables all interrupts}$												
	When IPEN	When IPEN = 1:												
	1 = Enables	1 = Enables all high priority interrupts												
	0 = Disables	0 = Disables all interrupts												
bit 6	PEIE/GIEL:	Peripheral Int	errupt Enab	ole bit										
	When IPEN	<u>= 0:</u>												
	$\perp = \text{Enables}$ 0 = Disables	s all unmasked	interrunts	interrupts										
	When IPEN		intorrupto											
	1 = Enables	all low priority	, peripheral	interrupts										
	0 = Disables	s all low priority	y peripheral	interrupts										
bit 5	TMROIE: TN	TMR0IE: TMR0 Overflow Interrupt Enable bit												
	1 = Enables the TMR0 overflow interrupt													
	0 = Disables the TMR0 overflow interrupt													
bit 4	INTOIE: INT	INTOIE: INTO External Interrupt Enable bit												
	1 = Enables the INTO external interrupt													
hit 3		ort Change Int	torrunt Engl	nla hit										
bit 0	1 - Enables the BB port change interrupt													
	0 = Disables the RB port change interrupt													
bit 2	TMROIF: TN	IR0 Overflow	Interrupt Fla	ag bit										
	1 = TMR0 register has overflowed (must be cleared in software)													
	0 = TMR0 re	egister did not	overflow											
bit 1	INTOIF: INT	0 External Inte	errupt Flag b	pit										
	1 = The INT 0 = The INT	0 external inte 0 external inte	rrupt occur	red (must b ot occur	e cleared in	software)								
bit 0	RBIF: RB P	ort Change Int	errupt Flag	bit										
	1 = At least	1 = At least one of the RB7:RB4 pins changed state (must be cleared in software)												
	0 = None of	the RB7:RB4	pins have c	hanged sta	te									
	Note:	A mismatch co mismatch cono	ondition will dition and a	continue to llow the bit	set this bit. to be cleare	Reading Po	ORTB will e	end the						

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented b	oit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

# 10.5 PORTE, TRISE and LATE Registers

Depending on the particular PIC18F4321 family device selected, PORTE is implemented in two different ways.

For 40/44-pin devices, PORTE is a 4-bit wide port. Three pins (RE0/RD/AN5, RE1/WR/AN6 and RE2/CS/ AN7) are individually configurable as inputs or outputs. These pins have Schmitt Trigger input buffers. When selected as analog inputs, these pins will read as '0'.

The corresponding data direction register is TRISE. Setting a TRISE bit (= 1) will make the corresponding PORTE pin an input (i.e., put the corresponding output driver in a high-impedance mode). Clearing a TRISE bit (= 0) will make the corresponding PORTE pin an output (i.e., put the contents of the output latch on the selected pin).

TRISE controls the direction of the RE pins, even when they are being used as analog inputs. The user must make sure to keep the pins configured as inputs when using them as analog inputs.

Note:	On a		Power-on	Reset,	eset, RE2:RE0		
	con	figu	ired as ana	log input	s.		

The upper four bits of the TRISE register also control the operation of the Parallel Slave Port. Their operation is explained in Register 10-1.

The Data Latch register (LATE) is also memory mapped. Read-modify-write operations on the LATE register, read and write the latched output value for PORTE.

The fourth pin of PORTE ( $\overline{\text{MCLR}}/\text{VPP}/\text{RE3}$ ) is an input only pin. Its operation is controlled by the MCLRE configuration bit. When selected as a port pin (MCLRE = 0), it functions as a digital input only pin; as such, it does not have TRIS or LAT bits associated with its operation. Otherwise, it functions as the device's Master Clear input. In either configuration, RE3 also functions as the programming voltage input during programming.

Note:	Or	n a Pow	er-on F	Reset,	RE	3 is enab	led as		
	а	digital	input	only	if	Master	Clear		
	functionality is disabled.								

### EXAMPLE 10-5: INITIALIZING PORTE

CLRF	PORTE	;	Initialize PORTE by
		;	clearing output
		;	data latches
CLRF	LATE	;	Alternate method
		;	to clear output
		;	data latches
MOVLW	0Ah	;	Configure A/D
MOVWF	ADCON1	;	for digital inputs
MOVLW	03h	;	Value used to
		;	initialize data
		;	direction
MOVWF	TRISE	;	Set RE<0> as inputs
		;	RE<1> as outputs
		;	RE<2> as inputs

# 10.5.1 PORTE IN 28-PIN DEVICES

For 28-pin devices, PORTE is only available when Master Clear functionality is disabled (MCLRE = 0). In these cases, PORTE is a single bit, input only port comprised of RE3 only. The pin operates as previously described.

FIGURE 10-3:	PARALLEL SLAVE PORT WRITE WAVEFORMS								
	Q1   Q2   Q3   Q4 Q1   Q2   Q3   Q4 Q1   Q2   Q3   Q4								
WR									
RD									
PORTD<7:0> -									
IBF									
OBF _									
PSPIF _									

### FIGURE 10-4: PARALLEL SLAVE PORT READ WAVEFORMS



#### TABLE 10-11: REGISTERS ASSOCIATED WITH PARALLEL SLAVE PORT

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
PORTD	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	52
LATD	PORTD Dat	ta Latch Regis	ster (Read a	nd Write to Da	ta Latch)				52
TRISD	PORTD Data Direction Control Register								52
PORTE	—	—	_	_	RE3	RE2	RE1	RE0	52
LATE	—	—	-	-	—	PORTE Dat (Read and )	52		
TRISE	IBF	OBF	IBOV	PSPMODE	—	TRISE2	TRISE1	TRISE0	52
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IF	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	49
PIR1	PSPIF <sup>(1)</sup>	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	52
PIE1	PSPIE <sup>(1)</sup>	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	52
IPR1	PSPIP <sup>(1)</sup>	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	52
ADCON1	_	_	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	51

**Legend:** — = unimplemented, read as '0'. Shaded cells are not used by the Parallel Slave Port.

Note 1: These bits are unimplemented on 28-pin devices and read as '0'.

# 11.0 TIMER0 MODULE

The Timer0 module incorporates the following features:

- Software selectable operation as a timer or counter in both 8-bit or 16-bit modes
- · Readable and writable registers
- Dedicated 8-bit, software programmable prescaler
- · Selectable clock source (internal or external)
- Edge select for external clock
- · Interrupt-on-overflow

The T0CON register (Register 11-1) controls all aspects of the module's operation, including the prescale selection. It is both readable and writable.

A simplified block diagram of the Timer0 module in 8-bit mode is shown in Figure 11-1. Figure 11-2 shows a simplified block diagram of the Timer0 module in 16-bit mode.

### REGISTER 11-1: T0CON: TIMER0 CONTROL REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
TMR0ON	T08BIT	TOCS	T0SE	PSA	T0PS2	T0PS1	T0PS0
bit 7							bit 0

- bit 7 **TMR0ON:** Timer0 On/Off Control bit
  - 1 = Enables Timer0
  - 0 = Stops Timer0
- bit 6 T08BIT: Timer0 8-Bit/16-Bit Control bit
  - 1 = Timer0 is configured as an 8-bit timer/counter
  - 0 = Timer0 is configured as a 16-bit timer/counter
- bit 5 **TOCS**: Timer0 Clock Source Select bit
  - 1 = Transition on T0CKI pin
  - 0 = Internal instruction cycle clock (CLKO)
- bit 4 TOSE: Timer0 Source Edge Select bit
  - 1 = Increment on high-to-low transition on T0CKI pin
  - 0 = Increment on low-to-high transition on T0CKI pin
- bit 3 **PSA**: Timer0 Prescaler Assignment bit
  - 1 = TImer0 prescaler is NOT assigned. Timer0 clock input bypasses prescaler.
  - 0 = Timer0 prescaler is assigned. Timer0 clock input comes from prescaler output.
- bit 2-0 TOPS2:TOPS0: Timer0 Prescaler Select bits
  - 111 = 1:256 Prescale value
  - 110 = 1:128 Prescale value
  - 101 = 1:64 Prescale value
  - 100 = 1:32 Prescale value
  - 011 = 1:16 Prescale value
  - 010 = 1:8 Prescale value
  - 001 = 1:4 Prescale value
  - 000 = 1:2 Prescale value

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented	bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

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REGISTER 18-2:	RCSTA: R	ECEIVE S	STATUS AN	ID CONTR	OL REGIS	TER						
	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-x				
	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D				
	bit 7		-					bit 0				
bit 7	SPEN: Ser	ial Port Ena	ıble bit									
	1 = Serial p 0 = Serial p	oort enabled oort disable	l (configures d (held in Re	RX/DT and set)	TX/CK pins	as serial po	ort pins)					
bit 6	RX9: 9-bit	Receive En	able bit									
	1 = Selects 0 = Selects	s 9-bit recep s 8-bit recep	ition ition									
bit 5	SREN: Sin	gle Receive	Enable bit									
	<u>Asynchronous mode:</u> Don't care.											
	Synchronous mode – Master:											
	<ul> <li>1 = Enables single receive</li> <li>0 = Disables single receive</li> <li>This bit is cleared after reception is complete</li> </ul>											
	I his bit is cleared after reception is complete. Synchronous mode – Slave:											
	Don't care.		<u>Slave.</u>									
bit 4	CREN: Co	ntinuous Re	ceive Enable	e bit								
	Asynchron	ous mode:										
	1 = Enable	s receiver										
	Svnchronous mode:											
	<u>Synchronous mode:</u> 1 = Enables continuous receive until enable bit CREN is cleared (CREN overrides SREN)											
	0 = Disables continuous receive											
bit 3	ADDEN: Address Detect Enable bit											
	Asynchronous mode 9-bit (RX9 = 1):											
	1 = Enables address detection, enables interrupt and loads the receive buffer when RSR<8>											
	is set 0 = Disables address detection, all bytes are received and ninth bit can be used as parity bit											
	0 = D is ables address detection, all bytes are received and ninth bit can be used as parity bit Asynchronous mode 9-bit (RX9 = 0):											
	Don't care.											
bit 2	FERR: Framing Error bit											
	1 = Framing error (can be updated by reading RCREG register and receiving next valid byte)											
bit 1	0 = 100 traming error											
DILI	UERR: Overrun Error bit											
	1 = 0 overrun error (can be cleared by clearing bit CREN) 0 = No overrun error											
bit 0	RX9D: 9th bit of Received Data											
	This can be address/data bit or a parity bit and must be calculated by user firmware.											
	Legend:											
	R = Reada	ble bit	W = W	/ritable bit	U = Unin	plemented	bit, read as	'0'				

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

	SYNC = 0, BRGH = 0, BRG16 = 0											
BAUD	Fosc = 40.000 MHz			Fosc = 20.000 MHz			Fosc = 10.000 MHz			Fosc = 8.000 MHz		
(К)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	—	_	_	—	_		_	_	_	_	_	_
1.2	—	—	—	1.221	1.73	255	1.202	0.16	129	1201	-0.16	103
2.4	2.441	1.73	255	2.404	0.16	129	2.404	0.16	64	2403	-0.16	51
9.6	9.615	0.16	64	9.766	1.73	31	9.766	1.73	15	9615	-0.16	12
19.2	19.531	1.73	31	19.531	1.73	15	19.531	1.73	7	—	_	_
57.6	56.818	-1.36	10	62.500	8.51	4	52.083	-9.58	2	—	_	_
115.2	125.000	8.51	4	104.167	-9.58	2	78.125	-32.18	1	—	—	_

TABI F 18-3.	BAUD BATES	FOR ASYNCHRONOUS MODES

	SYNC = 0, BRGH = 0, BRG16 = 0											
BAUD	Fos	c = 4.000	MHz	Fos	c = 2.000	MHz	Fosc = 1.000 MHz					
(K)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)			
0.3	0.300	0.16	207	300	-0.16	103	300	-0.16	51			
1.2	1.202	0.16	51	1201	-0.16	25	1201	-0.16	12			
2.4	2.404	0.16	25	2403	-0.16	12	—	—	—			
9.6	8.929	-6.99	6	—	—	—	—	—	—			
19.2	20.833	8.51	2	—	_	—	—	_	_			
57.6	62.500	8.51	0	—	—	—	—	—	—			
115.2	62.500	-45.75	0	—	_	_	—	_	_			

	<b>SYNC =</b> 0, <b>BRGH =</b> 1, <b>BRG16 =</b> 0											
BAUD RATE (K)	Fosc = 40.000 MHz			Fosc = 20.000 MHz			Fosc = 10.000 MHz			Fosc = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	_	_	_	_	_	_	_	_	_		_	_
1.2	—	_	—		—	—	—	—	—	—	—	—
2.4	—	_	—		—	—	2.441	1.73	255	2403	-0.16	207
9.6	9.766	1.73	255	9.615	0.16	129	9.615	0.16	64	9615	-0.16	51
19.2	19.231	0.16	129	19.231	0.16	64	19.531	1.73	31	19230	-0.16	25
57.6	58.140	0.94	42	56.818	-1.36	21	56.818	-1.36	10	55555	3.55	8
115.2	113.636	-1.36	21	113.636	-1.36	10	125.000	8.51	4	—	_	—

	SYNC = 0, BRGH = 1, BRG16 = 0										
BAUD	Foso	c = 4.000	MHz	Fos	c = 2.000	MHz	Fosc = 1.000 MHz				
(K)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)		
0.3	—	_	_		_	_	300	-0.16	207		
1.2	1.202	0.16	207	1201	-0.16	103	1201	-0.16	51		
2.4	2.404	0.16	103	2403	-0.16	51	2403	-0.16	25		
9.6	9.615	0.16	25	9615	-0.16	12	—	—	—		
19.2	19.231	0.16	12	—	—	—	—	—	—		
57.6	62.500	8.51	3	—	—	—	—	—	—		
115.2	125.000	8.51	1	—	—	_	—	_	_		

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# 20.0 COMPARATOR MODULE

The analog comparator module contains two comparators that can be configured in a variety of ways. The inputs can be selected from the analog inputs multiplexed with pins RA0 through RA5, as well as the on-chip voltage reference (see Section 21.0 "Comparator Voltage Reference Module"). The digital outputs (normal or inverted) are available at the pin level and can also be read through the control register.

The CMCON register (Register 20-1) selects the comparator input and output configuration. Block diagrams of the various comparator configurations are shown in Figure 20-1.

### REGISTER 20-1: CMCON: COMPARATOR CONTROL REGISTER

R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1	R/W-1
C2OUT	C10UT	C2INV	C1INV	CIS	CM2	CM1	CM0
bit 7							bit 0

bit 7	C2OUT: Comparator 2 Output bit	
	<u>When C2INV = 0:</u>	
	1 = C2 VIN + > C2 VIN	
	0 = C2 VIN + < C2 VIN	
	$\frac{\text{When C2INV} = 1:}{22 \text{ Max}}$	
	1 = G2  VIN + < G2  VIN	
L:1 C	0 = 62  Vin + 362  Vin	
	$\frac{\text{When C   INV = 0:}}{1 - C1 \text{ Vint}}$	
	0 = C1  VIN + < C1  VIN	
	When $C1INV = 1$ :	
	1 = C1 VIN + < C1 VIN -	
	0 = C1 VIN + > C1 VIN -	
bit 5	C2INV: Comparator 2 Output Inversion bit	
	1 = C2 output inverted	
	0 = C2 output not inverted	
bit 4	C1INV: Comparator 1 Output Inversion bit	
	1 = C1 output inverted	
	0 = C1 output not inverted	
bit 3	CIS: Comparator Input Switch bit	
	<u>When CM2:CM0 = 110:</u>	
	1 = C1 VIN- connects to RA3/AN3/VREF+	
	$C_2$ VIN- connects to RA2/AN2/VREF-/CVREF	
	C2 VIN- connects to RA1/AN1	
bit 2-0	CM2:CM0: Comparator Mode bits	
	Figure 20-1 shows the Comparator modes and the CM2:CM0 bit settings.	
	l egend:	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented b	oit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

# 20.9 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 20-4. Since the analog pins are connected to a digital output, they have reverse biased diodes to VDD and Vss. The analog input, therefore, must be between Vss and VDD. If the input voltage deviates from this

range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up condition may occur. A maximum source impedance of 10 k $\Omega$  is recommended for the analog sources. Any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current.

FIGURE 20-4: COMPARATOR ANALOG INPUT MODEL



TABLE 20-1: REGISTERS ASSOCIATED WITH COMPARATOR MODULE	TABLE 20-1:	<b>REGISTERS ASSOCIATED WITH COMPARATOR MODULE</b>
---	-------------	--

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page	
CMCON	C2OUT	C1OUT	C2INV	C1INV	CIS	CM2	CM1	CM0	51	
CVRCON	CVREN	CVROE	CVRR	CVRSS	CVR3	CVR2	CVR1	CVR0	51	
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	52	
PIR2	OSCFIF	CMIF	_	EEIF	BCLIF	HLVDIF	TMR3IF	CCP2IF	52	
PIE2	OSCFIE	CMIE	_	EEIE	BCLIE	HLVDIE	TMR3IE	CCP2IE	52	
IPR2	OSCFIP	CMIP	_	EEIP	BCLIP	HLVDIP	TMR3IP	CCP2IP	52	
PORTA	RA7 <sup>(1)</sup>	RA6 <sup>(1)</sup>	RA5	RA4	RA3	RA2	RA1	RA0	52	
LATA	LATA7 <sup>(1)</sup>	LATA6 <sup>(1)</sup>	PORTA Da	PORTA Data Latch Register (Read and Write to Data Latch)						
TRISA	TRISA7 <sup>(1)</sup>	TRISA6 <sup>(1)</sup>	PORTA Da	ta Direction	Control Re	gister			52	

Legend: — = unimplemented, read as '0'. Shaded cells are unused by the comparator module.

**Note 1:** PORTA<7:6> and their direction and latch bits are individually configured as port pins based on various primary oscillator modes. When disabled, these bits read as '0'.

# 22.2 HLVD Setup

The following steps are needed to set up the HLVD module:

- 1. Disable the module by clearing the HLVDEN bit (HLVDCON<4>).
- 2. Write the value to the HLVDL3:HLVDL0 bits that selects the desired HLVD trip point.
- Set the VDIRMAG bit to detect high voltage (VDIRMAG = 1) or low voltage (VDIRMAG = 0).
- 4. Enable the HLVD module by setting the HLVDEN bit.
- 5. Clear the HLVD interrupt flag (PIR2<2>), which may have been set from a previous interrupt.
- Enable the HLVD interrupt if interrupts are desired by setting the HLVDIE and GIE bits (PIE<2> and INTCON<7>). An interrupt will not be generated until the IRVST bit is set.

### 22.3 Current Consumption

When the module is enabled, the HLVD comparator and voltage divider are enabled and will consume static current. The total current consumption, when enabled, is specified in electrical specification parameter D022B. Depending on the application, the HLVD module does not need to be operating constantly. To decrease the current requirements, the HLVD circuitry may only need to be enabled for short periods where the voltage is checked. After doing the check, the HLVD module may be disabled.

## 22.4 HLVD Start-up Time

The internal reference voltage of the HLVD module, specified in electrical specification parameter D420, may be used by other internal circuitry, such as the Programmable Brown-out Reset. If the HLVD or other circuits using the voltage reference are disabled to lower the device's current consumption, the reference voltage circuit will require time to become stable before a low or high-voltage condition can be reliably detected. This start-up time, TIRVST, is an interval that is independent of device clock speed. It is specified in electrical specification parameter 36.

The HLVD interrupt flag is not enabled until TIRVST has expired and a stable reference voltage is reached. For this reason, brief excursions beyond the set point may not be detected during this interval. Refer to Figure 22-2 or Figure 22-3.





# 23.3 Two-Speed Start-up

The Two-Speed Start-up feature helps to minimize the latency period from oscillator start-up to code execution by allowing the microcontroller to use the INTOSC oscillator as a clock source until the primary clock source is available. It is enabled by setting the IESO configuration bit.

Two-Speed Start-up should be enabled only if the primary oscillator mode is LP, XT, HS or HSPLL (crystal-based modes). Other sources do not require an OST start-up delay; for these, Two-Speed Start-up should be disabled.

When enabled, Resets and wake-ups from Sleep mode cause the device to configure itself to run from the internal oscillator block as the clock source, following the time-out of the Power-up Timer after a Power-on Reset is enabled. This allows almost immediate code execution while the primary oscillator starts and the OST is running. Once the OST times out, the device automatically switches to PRI\_RUN mode.

To use a higher clock speed on wake-up, the INTOSC or postscaler clock sources can be selected to provide a higher clock speed by setting bits, IRCF2:IRCF0, immediately after Reset. For wake-ups from Sleep, the INTOSC or postscaler clock sources can be selected by setting the IRCF2:IRCF0 bits prior to entering Sleep mode. In all other power-managed modes, Two-Speed Startup is not used. The device will be clocked by the currently selected clock source until the primary clock source becomes available. The setting of the IESO bit is ignored.

### 23.3.1 SPECIAL CONSIDERATIONS FOR USING TWO-SPEED START-UP

While using the INTOSC oscillator in Two-Speed Startup, the device still obeys the normal command sequences for entering power-managed modes, including multiple SLEEP instructions (refer to **Section 3.1.4 "Multiple Sleep Commands"**). In practice, this means that user code can change the SCS1:SCS0 bit settings or issue SLEEP instructions before the OST times out. This would allow an application to briefly wake-up, perform routine "housekeeping" tasks and return to Sleep before the device starts to operate from the primary oscillator.

User code can also check if the primary clock source is currently providing the device clocking by checking the status of the OSTS bit (OSCCON<3>). If the bit is set, the primary oscillator is providing the clock. Otherwise, the internal oscillator block is providing the clock during wake-up from Reset or Sleep mode.



# 25.7 MPLAB ICE 2000 High-Performance In-Circuit Emulator

The MPLAB ICE 2000 In-Circuit Emulator is intended to provide the product development engineer with a complete microcontroller design tool set for PICmicro microcontrollers. Software control of the MPLAB ICE 2000 In-Circuit Emulator is advanced by the MPLAB Integrated Development Environment, which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICE 2000 is a full-featured emulator system with enhanced trace, trigger and data monitoring features. Interchangeable processor modules allow the system to be easily reconfigured for emulation of different processors. The architecture of the MPLAB ICE 2000 In-Circuit Emulator allows expansion to support new PICmicro microcontrollers.

The MPLAB ICE 2000 In-Circuit Emulator system has been designed as a real-time emulation system with advanced features that are typically found on more expensive development tools. The PC platform and Microsoft<sup>®</sup> Windows<sup>®</sup> 32-bit operating system were chosen to best make these features available in a simple, unified application.

# 25.8 MPLAB ICE 4000 High-Performance In-Circuit Emulator

The MPLAB ICE 4000 In-Circuit Emulator is intended to provide the product development engineer with a complete microcontroller design tool set for high-end PICmicro MCUs and dsPIC DSCs. Software control of the MPLAB ICE 4000 In-Circuit Emulator is provided by the MPLAB Integrated Development Environment, which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICE 4000 is a premium emulator system, providing the features of MPLAB ICE 2000, but with increased emulation memory and high-speed performance for dsPIC30F and PIC18XXXX devices. Its advanced emulator features include complex triggering and timing, and up to 2 Mb of emulation memory.

The MPLAB ICE 4000 In-Circuit Emulator system has been designed as a real-time emulation system with advanced features that are typically found on more expensive development tools. The PC platform and Microsoft Windows 32-bit operating system were chosen to best make these features available in a simple, unified application.

# 25.9 MPLAB ICD 2 In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD 2, is a powerful, low-cost, run-time development tool, connecting to the host PC via an RS-232 or high-speed USB interface. This tool is based on the Flash PICmicro MCUs and can be used to develop for these and other PICmicro MCUs and dsPIC DSCs. The MPLAB ICD 2 utilizes the in-circuit debugging capability built into the Flash devices. This feature, along with Microchip's In-Circuit Serial Programming<sup>™</sup> (ICSP<sup>™</sup>) protocol, offers cost-effective, in-circuit Flash debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by setting breakpoints, single stepping and watching variables, and CPU status and peripheral registers. Running at full speed enables testing hardware and applications in real time. MPLAB ICD 2 also serves as a development programmer for selected PICmicro devices.

# 25.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at VDDMIN and VDDMAX for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages and a modular, detachable socket assembly to support various package types. The ICSP™ cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PICmicro devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices and incorporates an SD/MMC card for file storage and secure data applications.



# 26.3 DC Characteristics: PIC18F2221/2321/4221/4321 (Industrial) PIC18LF2221/2321/4221/4321 (Industrial) (Continued)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial					
Param No.	Symbol	Characteristic	Min	Мах	Units	Conditions		
	Vol	Output Low Voltage			<	$\bigwedge \lor$		
D080		I/O ports	—	0.6	X 7	IOL = 8,5 mA, VDD = 4.5V, 40°€ to +85°C		
D083		OSC2/CLKO (RC, RCIO, EC, ECIO modes)	—	0.6	V),	OL = 1.6 mA, VDD = 4.5V, 40°C to +85°C		
	Vон	Output High Voltage <sup>(3)</sup>						
D090		I/O ports	VDD - 0.7		⊳`v	IOH = -3.0 mA, VDD = 4.5V, -40°С to +85°С		
D092		OSC2/CLKO (RC, RCIO, EC, ECIO modes)	VDD - 0.7	$\rightarrow$	V	IOH = -1.3 mA, VDD = 4.5V, -40°С to +85°С		
		Capacitive Loading Specs on Output Pins						
D100	Cosc2	OSC2 pin		15	pF	In XT, HS and LP modes when external clock is used to drive OSC1		
D101	Сю	All I/O pins and OSC2 (in RC mode)	$\rightarrow$ –	50	pF	To meet the AC Timing Specifications		
D102	Св	SCL, SDA	—	400	pF	I <sup>2</sup> C <sup>™</sup> Specification		

Note 1: In RC oscillator configuration, the OSC1/CLKI pin is a Schmitt Trigger input. It is not recommended that the PICmicro<sup>®</sup> device be driven with an external clock while in RC mode.

- 2: The leakage current on the MOLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
- 3: Negative current is defined as current sourced by the pin.

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated)Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial					
Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions	
		Data EEPROM Memory						
D120	ED	Byte Endurance	1M	10M	—	E/W	-40°C to +85°C	
D121	Vdrw	VDD for Read/Write	VMIN	_	5.5	V	Using EECON to read/write, VMHU = Minimum operating Voltage	
D122	TDEW	Erase/Write Cycle Time	_	4	_	ms		
D123	TRETD	Characteristic Retention	40	—	-<	Year	Provided no other specifications are violated	
D124	TREF	Number of Total Erase/Write Cycles before Refresh <sup>(1)</sup>	100K	1M	$\langle \mathcal{O} \rangle$	ÈW	-40°C to +85°C	
D125	IDDP	Supply Current during Programming	—	10	$\searrow$	mA		
		Program Flash Memory			Ľ			
D130	Eр	Cell Endurance	10K <	K100K		E/W	-40°C to +85°C	
D131	Vpr	VDD for Read	VMIN	$\searrow$	5.5	V	VMIN = Minimum operating voltage	
D132B	VPEW	VDD for Self-Timed Write	VMIN	<u> </u>	5.5	V	VMIN = Minimum operating voltage	
D133A	Tiw	Self-Timed Write Cycle Time	$\searrow$	2	—	ms		
D134	TRETD	Characteristic Retention	40	100	_	Year	Provided no other specifications are violated	
D135	IDDP	Supply Current during	—	10	-	mA		

#### TABLE 26-1: MEMORY PROGRAMMING REQUIREMENTS

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Refer to Section 7.7. "Using the Data EEPROM" for a more detailed discussion on data EEPROM endurance.

28-Lead Plastic Small Outline (SO) - Wide, 300 mil Body (SOIC)



	INCHES*			MILLIMETERS			
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins n		28			28		
Pitch	р		.050			1.27	
Overall Height	А	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.288	.295	.299	7.32	7.49	7.59
Overall Length	D	.695	.704	.712	17.65	17.87	18.08
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle Top	φ	0	4	8	0	4	8
Lead Thickness	С	.009	.011	.013	0.23	0.28	0.33
Lead Width		.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top		0	12	15	0	12	15
Mold Draft Angle Bottom		0	12	15	0	12	15

\* Controlling Parameter § Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-013

Drawing No. C04-052

DEVICE

# APPENDIX A: REVISION HISTORY

# **Revision A (July 2005)**

Original data sheet for PIC18F2221/2321/4221/4321 devices.

### TABLE B-1:

# DIFFERENCES The differences between the devices listed in this data

**APPENDIX B:** 

sheet are shown in Table B-1.

**DEVICE DIFFERENCES** Features PIC18F2221 PIC18F2321 PIC18F4221 PIC18F4321 Program Memory (Bytes) 4096 8192 4096 8192 4096 Program Memory (Instructions) 2048 4096 2048 Interrupt Sources 19 20 19 20 I/O Ports Ports A, B, C, (E) Ports A, B, C, (E) Ports A, B, C, D, E Ports A, B, C, D, E Capture/Compare/PWM Modules 2 2 1 1 Enhanced Capture/Compare/ 0 0 1 1 **PWM Modules** Parallel Communications (PSP) No No Yes Yes 10-Bit Analog-to-Digital Module 10 input channels 10 input channels 13 input channels 13 input channels 28-pin SPDIP 28-pin SPDIP 40-pin PDIP 40-pin PDIP Packages 28-pin SOIC 28-pin SOIC 44-pin TQFP 44-pin TQFP 28-pin QFN 28-pin QFN 44-pin QFN 44-pin QFN